

Title (en)

Arrangement of a relay with a plug-in adapter and method of manufacturing this arrangement

Title (de)

Anordnung eines Relais mit einem Steckadapter und Verfahren zur Herstellung dieser Anordnung

Title (fr)

Agencement d'un relais avec un adaptateur à fiches et procédé pour la fabrication de cet agencement

Publication

EP 0713233 A3 19980304 (DE)

Application

EP 95116492 A 19951019

Priority

DE 4437954 A 19941024

Abstract (en)

[origin: DE4437954C1] The solder connection pins (13) protrude from the underside of the baseplate (12) of the relay (1) which is sealed with resin over a system of channels or ribs (14). The adaptor (2) is formed of a pedestal (20) of insulating material with inserted or embedded conductive segments (25) of a one-piece stamping (24) comprising flat pins (26) and intermediate bars (28). The pedestal incorporates open chambers (30) for e.g. spark-quenching resistors (3), and holes (27) are provided in the stamping for the pins of the relay which are soldered to the conductive segments before the pedestal is filled with resin.

IPC 1-7

H01H 50/02; **H01H 11/00**; **H01H 50/04**

IPC 8 full level

H01H 45/14 (2006.01); **H01H 11/00** (2006.01); **H01H 45/02** (2006.01); **H01H 45/04** (2006.01); **H01H 49/00** (2006.01); **H01H 50/02** (2006.01); **H01H 50/04** (2006.01); **H01R 13/66** (2006.01); **H01R 31/06** (2006.01); **H01R 13/52** (2006.01)

CPC (source: EP US)

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Citation (search report)

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- [A] EP 0053870 A1 19820616 - IDEC IZUMI CORP [JP]
- [A] US 4400761 A 19830823 - HAYDEN RODNEY [CA], et al
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DOCDB simple family (publication)

DE 4437954 C1 19960208; DE 59506944 D1 19991104; EP 0713233 A2 19960522; EP 0713233 A3 19980304; EP 0713233 B1 19990929; JP H08255543 A 19961001; US 5579211 A 19961126

DOCDB simple family (application)

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